

**Materials and Finish**

Housing Material:  
high temp. thermoplastic,  
(reflow process compatible)  
UL 94V-0 rated, black color

Recommended Reflow Temperature:  
230°C for 30 seconds,  
260°C max.

Design meets UL 1863 Sec. 8  
Electrical Probe and Sec. 20  
Child Finger test requirements

Shield Material:  
copper alloy, 0.20mm thick,  
nickel plated 90u" min,

Contact Material: phosphor bronze

Contact Plating Options:  
Standard: 0.0001" Nickel  
Plating, Selective Plating  
Gold Flash on Contact  
Area, Tin/Lead on Termination End

50: 0.0001" Nickel Plating,  
Selective Plating 0.000050"  
Gold on Contact Area to  
Comply with FCC Requirements  
Under No. 47 C.F.R. Part 68,  
Subpart F, Tin/Lead on  
Termination End

**Electrical Characteristics**

Insulation Resistance:  
500 Megohms min.

Dielectric Withstanding Voltage:  
1000V rms, 60Hz

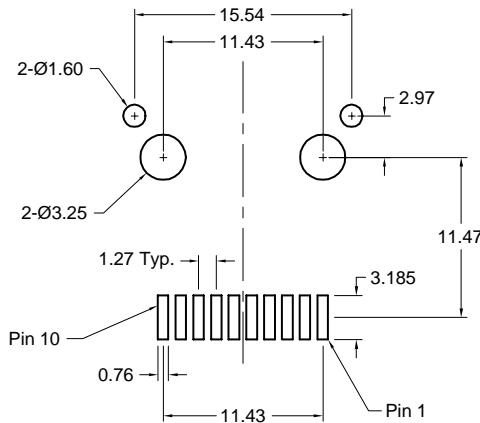
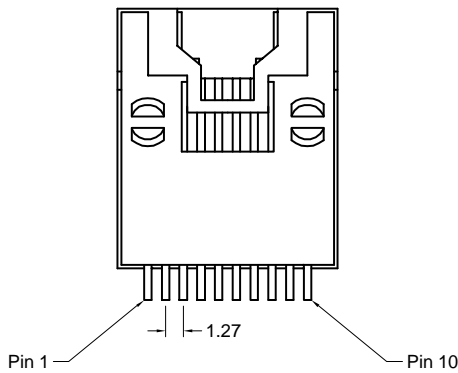
Contact Resistance:  
20 milliohms max.

Current Rating: 1.5 Amps

Durability Rating:  
1000 mating cycles min.

Operating Temperature:  
-40°C to +85°C

**Recommended PCB Layout  
(top view)**



Part Number	Contact Area Plating Finish
GM-SMT2-S-1010	15u" Gold (standard)
GM-SMT2-S-1010-50	50u" Gold (50 option)

CSA Certified File No. LR78160  
UL Recognized File No. E134345

REVISION	DATE	DESCRIPTION	DRAWN BY	CHECKED BY	UNITS
A4	3/20/02	ref ECD #01-199	C. Leiva		mm
A5	6/4/02	ref ECD #02-038	REVISED BY	APPROVED BY	DATE
B1	7/12/02	ref ECD #02-072	C. Leiva		9/23/97

GM-SMT2-S-1010

Right Angle Modular Jack, Shielded  
10 position, 10 contacts, Surface Mount

